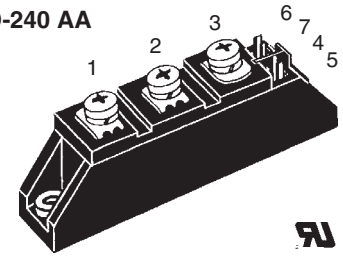
# Thyristor Modules
# Thyristor/Diode Modules

$I_{TRMS}$ = 2x100 A
$I_{TAVM}$ = 2x64 A
$V_{RRM}$ = 800-1800 V

TO-240 AA

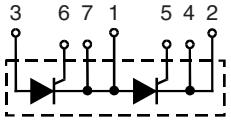



| $V_{RSM}$ $V_{DSM}$ | $V_{RRM}$ $V_{DRM}$ | Type | | | | | |
|---|---|---|---|---|---|---|---|
| V | V | Version | 1 B | 8 B | Version | 1 B | 8 B |
| 900 | 800 | MCC 56-08 | io1 B / | io8 B | MCD 56-08 | io1 B / | io8 B |
| 1300 | 1200 | MCC 56-12 | io1 B / | io8 B | MCD 56-12 | io1 B / | io8 B |
| 1500 | 1400 | MCC 56-14 | io1 B / | io8 B | MCD 56-14 | io1 B / | io8 B |
| 1700 | 1600 | MCC 56-16 | io1 B / | io8 B | MCD 56-16 | io1 B / | io8 B |
| 1900 | 1800 | MCC 56-18 | io1 B / | io8 B | MCD 56-18 | io1 B / | io8 B |

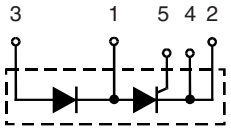
| Symbol | Conditions | | Maximum Ratings | |
|---|---|---|---|---|
| $I_{TRMS}$, $I_{FRMS}$ | $T_{VJ} = T_{VJM}$ | | 100 | A |
| $I_{TAVM}$, $I_{FAVM}$ | $T_C$ = 83°C; 180° sine | | 64 | A |
| | $T_C$ = 85°C; 180° sine | | 60 | A |
| $I_{TSM}$, $I_{FSM}$ | $T_{VJ}$ = 45°C; | t = 10 ms (50 Hz), sine | 1500 | A |
| | $V_R$ = 0 | t = 8.3 ms (60 Hz), sine | 1600 | A |
| | $T_{VJ} = T_{VJM}$ | t = 10 ms (50 Hz), sine | 1350 | A |
| | $V_R$ = 0 | t = 8.3 ms (60 Hz), sine | 1450 | A |
| $\int i^2dt$ | $T_{VJ}$ = 45°C | t = 10 ms (50 Hz), sine | 11 200 | $A^2s$ |
| | $V_R$ = 0 | t = 8.3 ms (60 Hz), sine | 10 750 | $A^2s$ |
| | $T_{VJ} = T_{VJM}$ | t = 10 ms (50 Hz), sine | 9100 | $A^2s$ |
| | $V_R$ = 0 | t = 8.3 ms (60 Hz), sine | 8830 | $A^2s$ |
| $(di/dt)_{cr}$ | $T_{VJ} = T_{VJM}$ | repetitive, $I_T$ = 150 A | 150 | A/µs |
| | f =50 Hz, $t_P$ = 200 µs | | | |
| | $V_D = {}^2/_3 V_{DRM}$ | | | |
| | $I_G$ = 0.45 A | non repetitive, $I_T = I_{TAVM}$ | 500 | A/µs |
| | $di_G/dt$ = 0.45 A/µs | | | |
| $(dv/dt)_{cr}$ | $T_{VJ} = T_{VJM}$; | $V_{DR} = {}^2/_3 V_{DRM}$ | 1000 | V/µs |
| | $R_{GK} = \infty$; method 1 (linear voltage rise) | | | |
| $P_{GM}$ | $T_{VJ} = T_{VJM}$; | $t_P$ = 30 µs | 10 | W |
| | $I_T = I_{TAVM}$; | $t_P$ = 300 µs | 5 | W |
| $P_{GAV}$ | | | 0.5 | W |
| $V_{RGM}$ | | | 10 | V |
| $T_{VJ}$ | | | -40...+125 | °C |
| $T_{VJM}$ | | | 125 | °C |
| $T_{stg}$ | | | -40...+125 | °C |
| $V_{ISOL}$ | 50/60 Hz, RMS; | t = 1 min | 3000 | V~ |
| | $I_{ISOL} \leq$ 1 mA; | t = 1 s | 3600 | V~ |
| $M_d$ | Mounting torque (M5) | | 2.5-4.0/22-35 | Nm/lb.in. |
| | Terminal connection torque (M5) | | 2.5-4.0/22-35 | Nm/lb.in. |
| Weight | Typical including screws | | 90 | g |

Data according to IEC 60747 and refer to a single thyristor/diode unless otherwise stated.
IXYS reserves the right to change limits, test conditions and dimensions

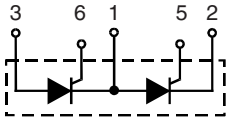
MCC Version 1 B



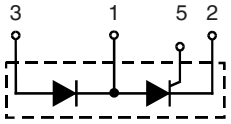

MCD Version 1 B




MCC Version 8 B




MCD Version 8 B




### Features

- International standard package, JEDEC TO-240 AA
- Direct copper bonded $Al_2O_3$ -ceramic base plate
- Planar passivated chips
- Isolation voltage 3600 V~
- UL registered, E 72873
- Gate-cathode twin pins for version 1B

### Applications

- DC motor control
- Softstart AC motor controller
- Light, heat and temperature control

### Advantages

- Space and weight savings
- Simple mounting with two screws
- Improved temperature and power cycling
- Reduced protection circuits

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| Symbol | Conditions | | Characteristic Values | |
|---|---|---|---|---|
| $I_{RRM}$, $I_{DRM}$ | $T_{VJ} = T_{VJM}$; $V_R = V_{RRM}$; $V_D = V_{DRM}$ | | 5 | mA |
| $V_T$, $V_F$ | $I_T/I_F$ = 200 A; $T_{VJ}$ = 25°C | | 1.57 | V |
| $V_{T0}$ | For power-loss calculations only ($T_{VJ}$ = 125°C) | | 0.85 | V |
| $r_T$ | | | 3.7 | mΩ |
| $V_{GT}$ | $V_D$ = 6 V; | $T_{VJ}$ = 25°C | 1.5 | V |
| | | $T_{VJ}$ = -40°C | 1.6 | V |
| $I_{GT}$ | $V_D$ = 6 V; | $T_{VJ}$ = 25°C | 100 | mA |
| | | $T_{VJ}$ = -40°C | 200 | mA |
| $V_{GD}$ | $T_{VJ} = T_{VJM}$; $V_D = {}^2/_3\ V_{DRM}$ | | 0.2 | V |
| $I_{GD}$ | | | 10 | mA |
| $I_L$ | $T_{VJ}$ = 25°C; $t_P$ = 10 µs; $V_D$ = 6 V<br>$I_G$ = 0.45 A; $di_G/dt$ = 0.45 A/µs | | 450 | mA |
| $I_H$ | $T_{VJ}$ = 25°C; $V_D$ = 6 V; $R_{GK}$ = ∞ | | 200 | mA |
| $t_{gd}$ | $T_{VJ}$ = 25°C; $V_D$ = ½ $V_{DRM}$<br>$I_G$ = 0.45 A; $di_G/dt$ = 0.45 A/µs | | 2 | µs |
| $t_q$ | $T_{VJ} = T_{VJM}$; $I_T$ = 150 A, $t_P$ = 200 µs; -di/dt = 10 A/µs<br>$V_R$ = 100 V; dv/dt = 20 V/µs; $V_D = {}^2/_3\ V_{DRM}$ | typ. | 150 | µs |
| $Q_S$ | $T_{VJ} = T_{VJM}$; $I_T$, $I_F$ = 50 A, -di/dt = 3 A/µs | | 100 | µC |
| $I_{RM}$ | | | 24 | A |
| $R_{thJC}$ | per thyristor/diode; DC current | other values see Fig. 8/9 | 0.45 | K/W |
| | per module | | 0.225 | K/W |
| $R_{thJK}$ | per thyristor/diode; DC current | | 0.65 | K/W |
| | per module | | 0.325 | K/W |
| $d_S$ | Creepage distance on surface | | 12.7 | mm |
| $d_A$ | Strike distance through air | | 9.6 | mm |
| a | Maximum allowable acceleration | | 50 | $m/s^2$ |

Optional accessories for module-type MCC 56 version 1 B
Keyed gate/cathode twin plugs with wire length = 350 mm, gate = yellow, cathode = red
Type **ZY 200L** (L = Left for pin pair 4/5) } UL 758, style 1385,
Type **ZY 200R** (R = right for pin pair 6/7) } CSA class 5851, guide 460-1-1

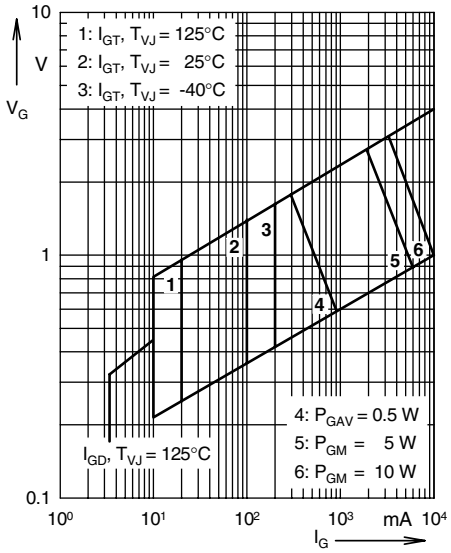



Fig. 1 Gate trigger characteristics

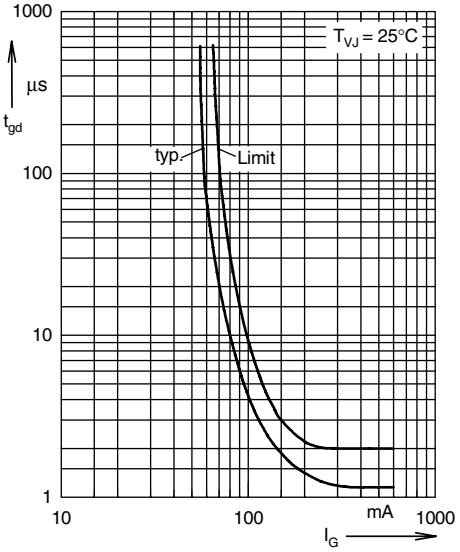
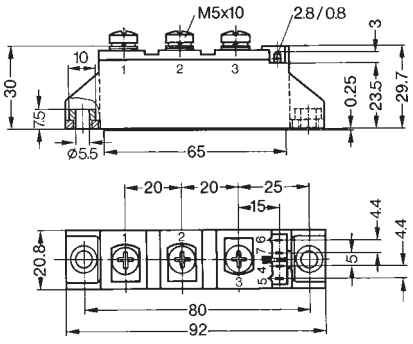


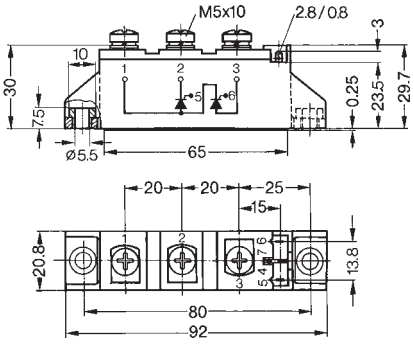

Fig. 2 Gate trigger delay time

**Dimensions in mm (1 mm = 0.0394")**

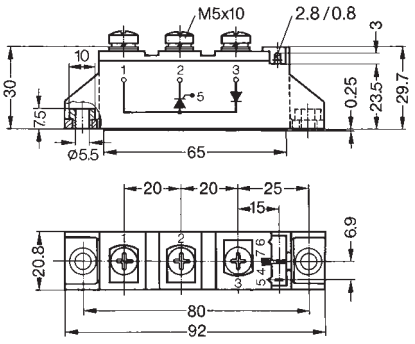
**MCC / MCD / MDC Version 1 B**




**MCC Version 8 B**




**MCD Version 8 B**




**Version 1 or 8 without B in typ designation = without insert in mountig holes**

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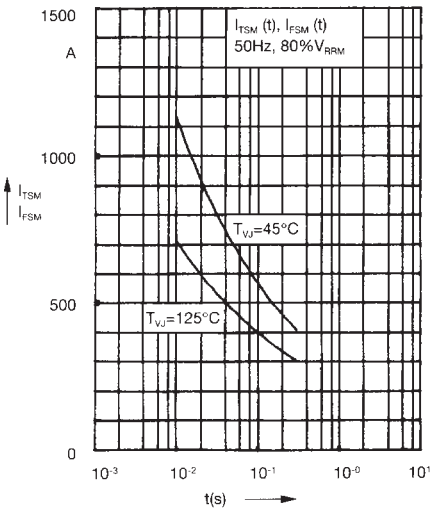


Fig. 3 Surge overload current
$I_{TSM}$, $I_{FSM}$: Crest value, t: duration

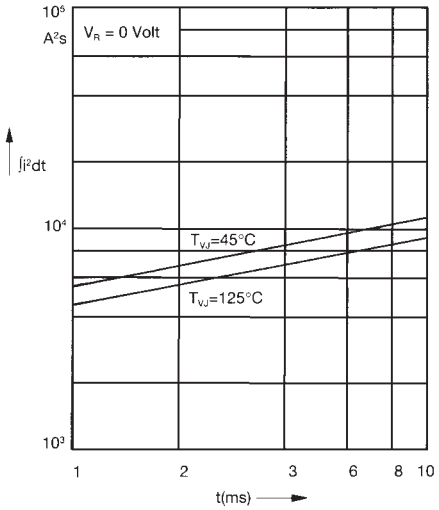


Fig. 4 $\int i^2dt$ versus time (1-10 ms)

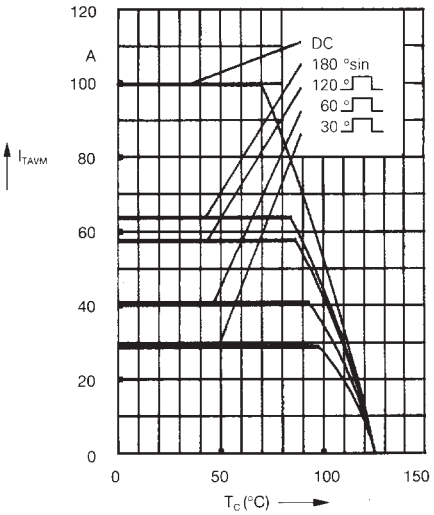


Fig. 4a Maximum forward current at case temperature

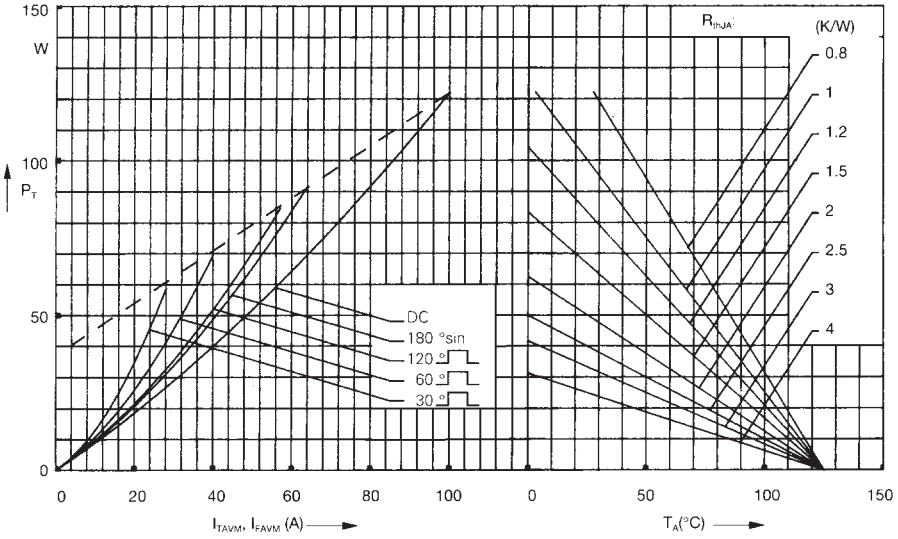


Fig. 5 Power dissipation versus on-state current and ambient temperature (per thyristor or diode)

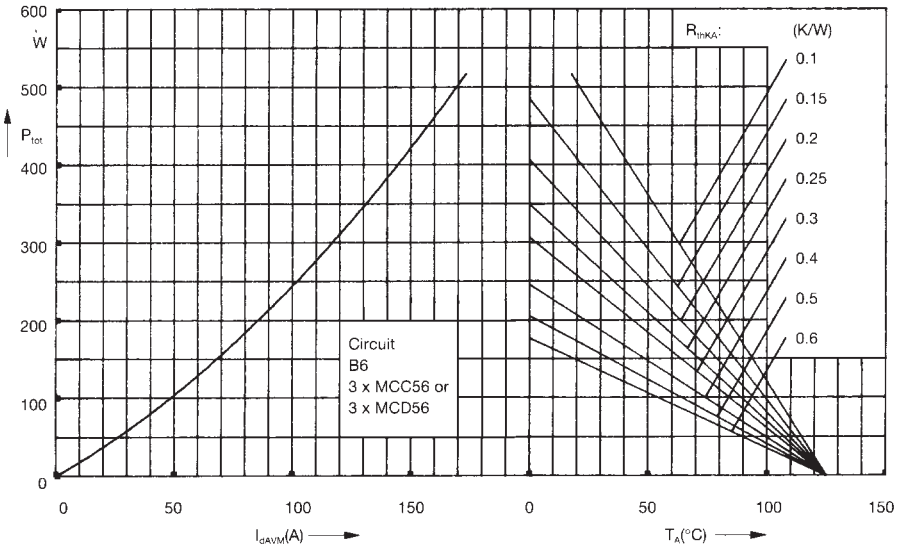


Fig. 6 Three phase rectifier bridge: Power dissipation versus direct output current and ambient temperature

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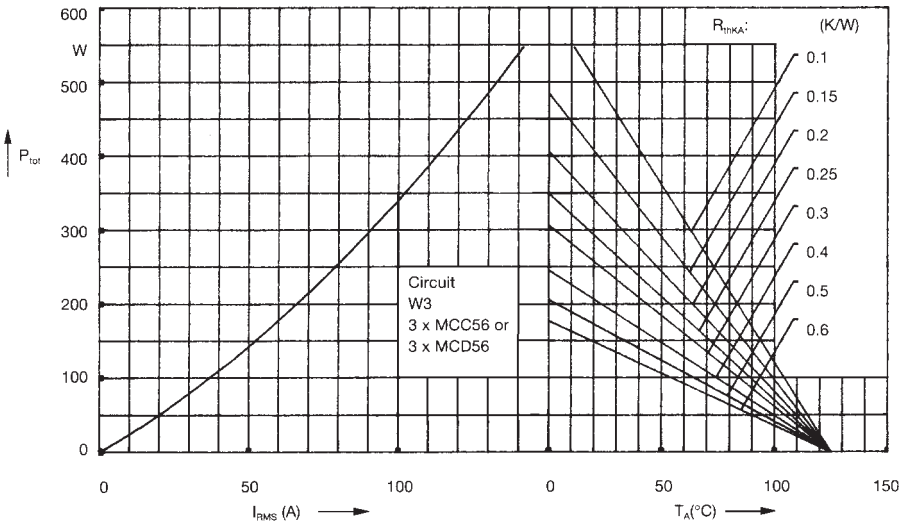


Fig. 7 Three phase AC-controller: Power dissipation versus RMS output current and ambient temperature

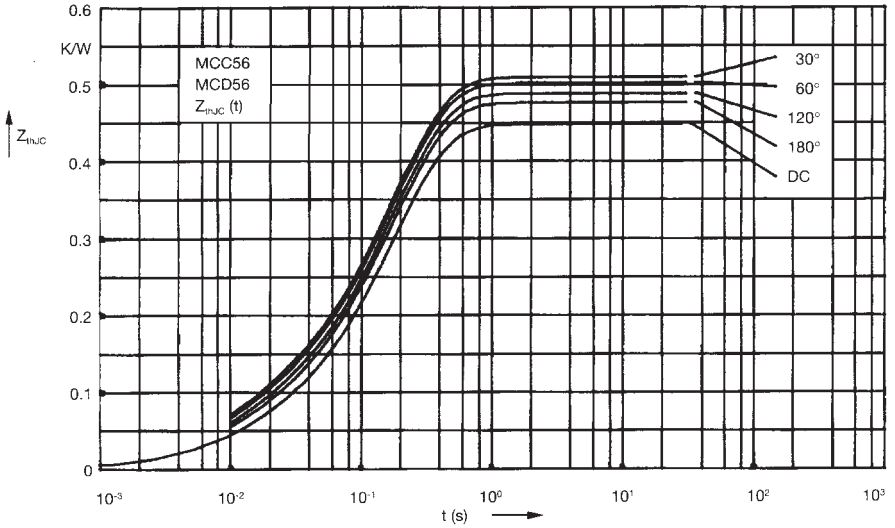


Fig. 8 Transient thermal impedance junction to case (per thyristor or diode)

$R_{thJC}$ for various conduction angles d:

| d | $R_{thJC}$ (K/W) |
|---|---|
| DC | 0.45 |
| 180° | 0.47 |
| 120° | 0.49 |
| 60° | 0.505 |
| 30° | 0.52 |

Constants for $Z_{thJC}$ calculation:

| i | $R_{thi}$ (K/W) | $t_i$ (s) |
|---|---|---|
| 1 | 0.014 | 0.015 |
| 2 | 0.026 | 0.0095 |
| 3 | 0.41 | 0.175 |

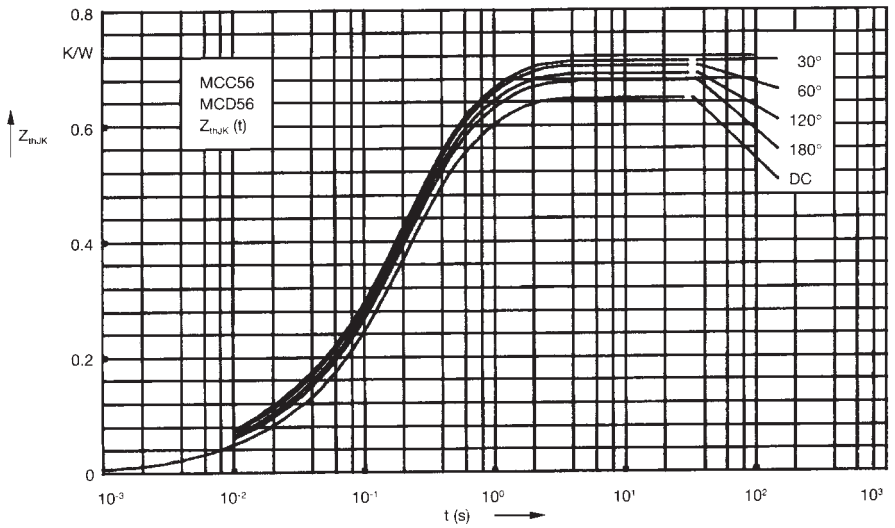


Fig. 9 Transient thermal impedance junction to heatsink (per thyristor or diode)

$R_{thJK}$ for various conduction angles d:

| d | $R_{thJK}$ (K/W) |
|---|---|
| DC | 0.65 |
| 180° | 0.67 |
| 120° | 0.69 |
| 60° | 0.705 |
| 30° | 0.72 |

Constants for $Z_{thJK}$ calculation:

| i | $R_{thi}$ (K/W) | $t_i$ (s) |
|---|---|---|
| 1 | 0.014 | 0.015 |
| 2 | 0.026 | 0.0095 |
| 3 | 0.41 | 0.175 |
| 4 | 0.2 | 0.67 |

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